United States Patents For "Leadframe AE Process"

QPL obtains United States Patents for its process for enhancement of adhesion properties for copper based leadframe applications.

QPL is proud to announce that it has obtained several United States Patents for its "Leadframe AE Process". The AE process provides the highest levels of reliability in plastic IC packaging (including the newest QFN and DFN packages) in relationship to moisture resistance and reduced delamination during solder reflow operations.The process achieves this by providing a chemical/mechanical bond between the leadframe and molding compound during the assembly of plastic integrated circuits (IC's). Additionally, the process provides enhancement of wirebond registration during the automatic wirebonding process.

"The feedback that we have received from our customers about this process has been extremely positive and we have been advised that products built with AE leadframes have been able to achieve unprecedented MSL levels", said Joe Martin, Chief Executive Officer of QPL.

The AE process is presently available for QFN, DFN, QFP, SOIC, PDIP, PLCC, SOT, SSOP packages.

For further details, please contact your nearest QPL sales office or http://qpl.com/eng/about/about_globe.html

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